SDAS224B - JUNE 1982 - REVISED NOVEMBER 1995

- Compare Two 8-Bit Words
- Choice of Totem-Pole or Open-Collector Outputs
- SN74ALS518 and 'ALS520 Have 20-kΩ
 Pullup Resistors on Q Inputs
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

TYPE	INPUT PULLUP RESISTOR	OUTPUT FUNCTION AND CONFIGURATION				
SN74ALS518	Yes	P = Q open collector				
'ALS520	Yes	P = Q totem pole				
SN74ALS521 [‡]	No	P = Q totem pole				

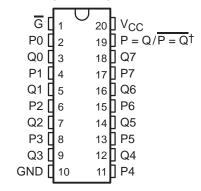
^{\$\}frac{1}{7}\$ SN74ALS521 is identical to 'ALS688.

description

These identity comparators perform comparisons on two 8-bit binary or BCD words. The SN74ALS518 provides P = Q outputs, while the 'ALS520 and SN74ALS521 provide $\overline{P} = \overline{Q}$ outputs. The SN74ALS518 has an open-collector output. The SN74ALS518 and 'ALS520 feature 20-k Ω pullup resistors on the Q inputs for analog or switch data.

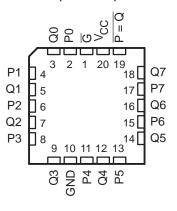
The SN54ALS520 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS518, SN74ALS520, and SN74ALS521 are characterized for operation from 0°C to 70°C.

SN54ALS520 . . . J PACKAGE SN74ALS518, SN74ALS520, SN74ALS521 . . . DW OR N PACKAGE (TOP VIEW)



 † P = Q for SN74ALS518 P = Q for 'ALS520 and SN74ALS521

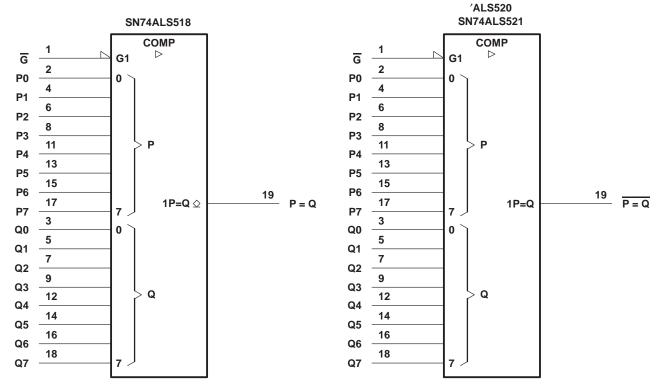
SN54ALS520 . . . FK PACKAGE (TOP VIEW)



FUNCTION TABLE

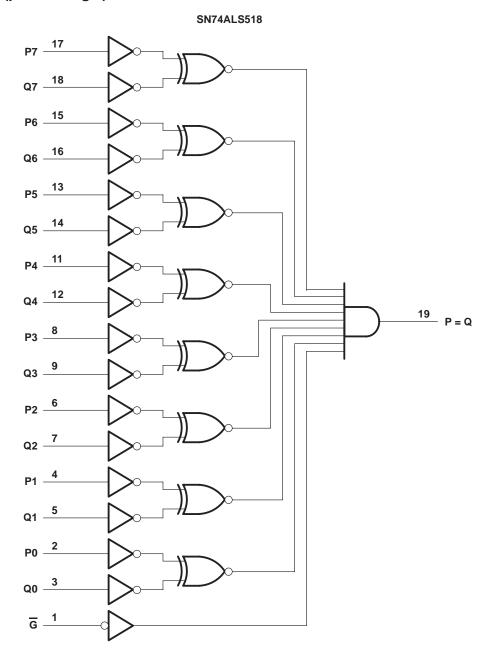
IN	PUTS	OUTPUTS				
DATA P, Q	ENABLE G	P = Q	P = Q			
P = Q	L	Н	L			
P > Q	L	L	Н			
P < Q	L	L	Н			
Х	Н	L	Н			

logic symbols†

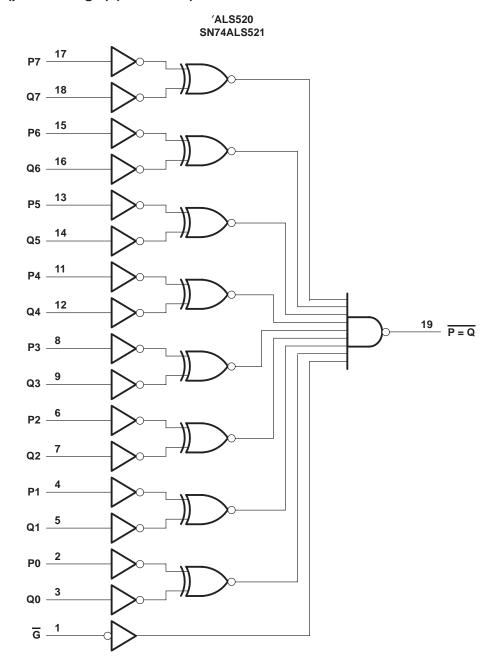


[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagrams (positive logic)



logic diagrams (positive logic) (continued)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	
Input voltage, V _I : Q inputs	V _{CC} + 0.5 V or 5.5 V, whichever is less
All other inputs	
Off-state output voltage	
Operating free-air temperature range, T _A : SN74ALS518	0°C to 70°C
Storage temperature range	

recommended operating conditions

		SN	74ALS5	18	UNIT
		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
Vон	High-level output voltage			5.5	V
loL	Low-level output current			24	mA
TA	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	TEST COM	DITIONS	SN	SN74ALS518		
	PARAMETER	TEST CONI	TEST CONDITIONS				
٧ıK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.5	V
loh		V _{CC} = 5.5 V,	V _{OH} = 5.5 V			0.1	mA
V/01		V00 - 45 V	I _{OL} = 12 mA		0.25	0.4	V
VOL		V _{CC} = 4.5 V	$I_{OL} = 24 \text{ mA}$		0.35	0.5	V
1.	Q inputs	V00 - 55 V	V _I = 5.5 V			0.1	mA
1 ₁	All other inputs	V _{CC} = 5.5 V	V _I = 7 V			0.1	IIIA
la c	Q inputs	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	V _I = 2.7 V			-0.2	mA
¹IН	All other inputs	V _{CC} = 5.5 V,	V = 2.7 V			20	μΑ
Lin	Q inputs	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	V _I = 0.4 V			-0.6	mA
IIL	All other inputs	V _{CC} = 5.5 V,	V = U.4 V			-0.1	IIIA
ICC		V _{CC} = 5.5 V,	See Note 1		11	17	mA

‡ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ}\text{C}$.

NOTE 1: ICC is measured with G grounded, and P and Q at 4.5 V.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

SN54ALS520, SN74ALS518, SN74ALS520, SN74ALS521 8-BIT IDENTITY COMPARATORS

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4.5 V to 5.5 V C_L = 50 pF, R_L = 680 Ω , T_A = MIN to MAX† SN74ALS518 MIN MAX		UNIT
t _{PLH}	D. a.r. O	Б. О	15	33	no
^t PHL	P or Q	P = Q	3	15	ns
t _{PLH}	G	P = Q	15	33	
t _{PHL}	J	Γ≅Q	3	15	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I : Q inputs of 'ALS520 V _{CC} + 0.5 V or 5.5 V, wh	ichever is less
All other inputs	7 V
Operating free-air temperature range, T _A : SN54ALS520	55°C to 125°C
SN74ALS520, SN74ALS521	. 0°C to 70°C
Storage temperature range – (65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	54ALS5	20	SN SN	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
ІОН	High-level output current			-1			-2.6	mA
loL	Low-level output current			12			24	mA
TA	Operating free-air temperature	-55		125	0		70	°C

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST COI	NDITIONS	SN	54ALS5	20		74ALS5 74ALS5		UNIT	
			MIN	TYP [†]	MAX	MIN	TYP [†]	MAX			
٧ıK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2)			
Vон		V45V	$I_{OH} = -1 \text{ mA}$	2.4	3.3					V	
		V _{CC} = 4.5 V	$I_{OH} = -2.6 \text{ mA}$				2.4	3.2			
V/01		V00 - 45 V	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V	
VOL		VCC = 4.5 V	I _{OL} = 24 mA					0.35	0.5]	
ı.	'ALS520 Q inputs	V00 - 5 5 V	V _I = 5.5 V			0.1			0.1	mA	
11	All other inputs	VCC = 5.5 V	V _I = 7 V			0.1			0.1	mA	
	'ALS520 Q inputs	V 55V	V- 2.7.V			-0.2			-0.2	mA	
lіН	All other inputs	$V_{CC} = 5.5 \text{ V},$	$V_1 = 2.7 \text{ V}$			20			20	μΑ	
	'ALS520 Q inputs	V 55V	V: 0.4.V			-0.6			-0.6	A	
IIL.	All other inputs	V _{CC} = 5.5 V,	$V_{ } = 0.4 \text{ V}$			-0.1			-0.1	mA	
10 [‡]		V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA	
'ALS520		V 55V	Coo Note 4		12	19		12	19	A	
ICC	SN74ALS521	V _{CC} = 5.5 V,	See Note 1		12	19		12	19	mA	

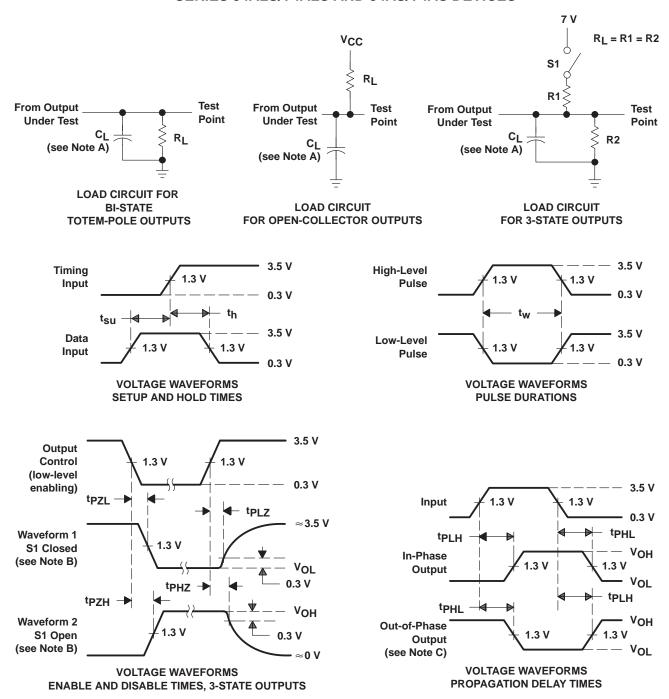
switching characteristics (see Figure 1)

PARAMETER	FROM	то	V _C C _L R _L T _A	UNIT			
	(INPUT)	(OUTPUT)	SN54ALS520		SN74ALS520 SN74ALS521		
			MIN	MAX	MIN	MAX	
t _{PLH}	D ar O		3	19	3	12	20
^t PHL	P or Q	P = Q	3	25	5	20	ns
tPLH	G	P = Q	2	18	2	12	ns
^t PHL	9	1 - 4	5	23	5	22	115

[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, los. NOTE 1: I_{CC} is measured with \overline{G} grounded, and P and Q at 4.5 V.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





1-Aug-2011

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-88691012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
5962-8869101RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SN54ALS520J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SN74ALS518DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS518DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS518DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS518N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS518NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS520DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS520DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS520DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS520DWR	ACTIVE	SOIC	DW	20		TBD	Call TI	Call TI	
SN74ALS520DWRE4	ACTIVE	SOIC	DW	20		TBD	Call TI	Call TI	
SN74ALS520DWRG4	ACTIVE	SOIC	DW	20		TBD	Call TI	Call TI	
SN74ALS520N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS520NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS520NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS520NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS520NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS521DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS521DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	





1-Aug-2011

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74ALS521DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS521DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS521DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS521DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS521N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS521NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS521NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS521NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS521NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54ALS520FK	ACTIVE	LCCC	FK	20	11	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54ALS520J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.





1-Aug-2011

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OTHER QUALIFIED VERSIONS OF SN54ALS520, SN74ALS520:

Catalog: SN74ALS520

Military: SN54ALS520

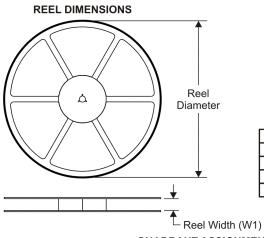
NOTE: Qualified Version Definitions:

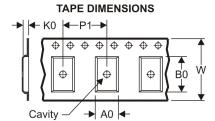
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 1-Aug-2011

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS520NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74ALS521DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS521NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 1-Aug-2011



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74ALS520NSR	SO	NS	20	2000	346.0	346.0	41.0	
SN74ALS521DWR	SOIC	DW	20	2000	346.0	346.0	41.0	
SN74ALS521NSR	SO	NS	20	2000	346.0	346.0	41.0	

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC—7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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